

September 1983 Revised January 2005

MM74HC164 8-Bit Serial-in/Parallel-out Shift Register

General Description

The MM74HC164 utilizes advanced silicon-gate CMOS technology. It has the high noise immunity and low consumption of standard CMOS integrated circuits. It also offers speeds comparable to low power Schottky devices.

This 8-bit shift register has gated serial inputs and CLEAR. Each register bit is a D-type master/slave flip-flop. Inputs A & B permit complete control over the incoming data. A LOW at either or both inputs inhibits entry of new data and resets the first flip-flop to the low level at the next clock pulse. A high level on one input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is HIGH or LOW, but only information meeting the setup and hold time requirements will be entered. Data is serially shifted in and out of the 8-bit register during the positive going transition of the clock pulse. Clear is independent of the clock and accomplished by a low level at the CLEAR input.

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

- Typical operating frequency: 50 MHz
- Typical propagation delay: 19 ns (clock to Q)
- Wide operating supply voltage range: 2V to 6V
- Low input current: 1 μA maximum
- Low quiescent supply current: 80 µA maximum (74HC Series)
- Fanout of 10 LS-TTL loads

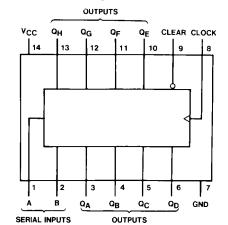
Ordering Code:

Order Number	Package Number	Package Description
MM74HC164M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC164MX_NL	M14A	Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC164MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC164MTCX_NL	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC164N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code. Pb-Free package per JEDEC J-STD-020B.

Connection Diagram

Top View



Truth Table

Inputs				Outputs				
Clear	Clock	Α	В	Q_A	Q_B	•••	Q _H	
L	Х	Х	Χ	L	L		L	
Н	L	Χ	X	Q_{AO}	Q_{BO}		Q_{HO}	
Н	↑	Н	Н	Н	Q_{An}		Q_{Gn}	
Н	↑	L	X	L	Q_{An}		Q_Gn	
Н	↑	Χ	L	L	Q_{An}		Q_{Gn}	

- H = HIGH Level (steady state), L = LOW Level (steady state)

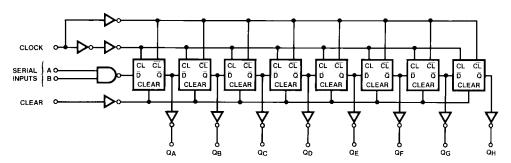
 X = Irrelevant (any input, including transitions)

 T = Transition from LOW-to-HIGH level.

- $Q_{AO},\ Q_{BO},\ Q_{HO}=\text{the level of }Q_{A},\ Q_{B},\ \text{or }Q_{H},\ \text{respectively, before the indi-}$ cated steady state input conditions were established.

 $Q_{An},\,Q_{Gn}=$ The level of Q_{A} or Q_{G} before the most recent \uparrow transition of the clock; indicated a one-bit shift.

Logic Diagram



Absolute Maximum Ratings(Note 1)

(Note 2)

(Soldering 10 seconds)

Supply Voltage (V_{CC}) -0.5 to +7.0V DC Input Voltage (V_{IN}) -1.5 to V_{CC} +1.5VDC Output Voltage (V_{OUT}) -0.5 to V_{CC} +0.5VClamp Diode Current (I_{IK}, I_{OK}) ±20 mA DC Output Current, per pin (I_{OUT}) ±25 mA DC V_{CC} or GND Current, per pin (I_{CC}) ±50 mA Storage Temperature Range (T_{STG}) $-65^{\circ}C$ to $+150^{\circ}C$ Power Dissipation (P_D) 600 mW (Note 3) S.O. Package only 500 mW Lead Temperature (T_L)

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V _{CC})	2	6	V
DC Input or Output Voltage			
(V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T _A)	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: –

12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

260°C

Symbol	Parameter	Conditions	V _{CC}	$T_A = 25^{\circ}C$		$T_A = -40 \text{ to } 85^{\circ}\text{C}$	T _A = -55 to 125°C	Units
Symbol		Conditions	▼CC	Тур	Guaranteed Limits			Ullits
V _{IH}	Minimum HIGH Level		2.0V		1.5	1.5	1.5	
	Input Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	
V _{IL}	Maximum LOW Level		2.0V		0.5	0.5	0.5	
	Input Voltage		4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	
V _{OH}	Minimum HIGH Level	$V_{IN} = V_{IH}$ or V_{IL}						
	Output Voltage	$ I_{OUT} \le 20 \ \mu A$	2.0V	2.0	1.9	1.9	1.9	
			4.5V	4.5	4.4	4.4	4.4	
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or V_{IL}						
		$ I_{OUT} \le 4.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	
		$ I_{OUT} \le 5.2 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	
V _{OL}	Maximum LOW Level	$V_{IN} = V_{IH}$ or V_{IL}						
	Output Voltage	$ I_{OUT} \le 20 \ \mu A$	2.0V	0	0.1	0.1	0.1	
			4.5V	0	0.1	0.1	0.1	
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or V_{IL}						
		$ I_{OUT} \le 4.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	
		$ I_{OUT} \le 5.2 \text{ mA}$	6.0V	0.2	0.26	0.33	0.4	
I _{IN}	Maximum Input	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μΑ
	Current							
I _{CC}	Maximum Quiescent	$V_{IN} = V_{CC}$ or GND	6.0V		8.0	80	160	μΑ
	Supply Current	$I_{OUT} = 0 \mu A$						

Note 4: For a power supply of 5V \pm 10% the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

 $V_{CC} = 5V$, $T_A = 25^{\circ}C$, $C_L = 15$ pF, $t_r = t_f = 6$ ns

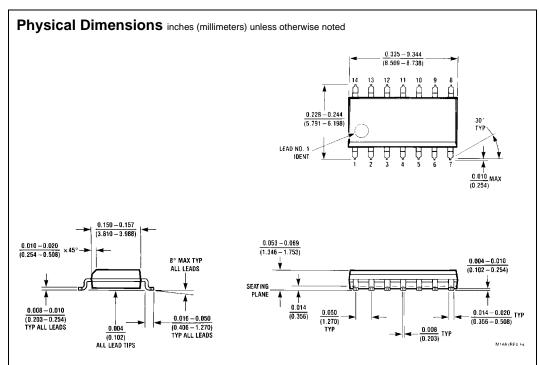
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
f_{MAX}	Maximum Operating Frequency			30	MHz
t _{PHL} , t _{PLH}	Maximum Propagation Delay Clock to Output		19	30	ns
t _{PHL}	Maximum Propagation Delay Clear to Output		23	35	ns
t _{REM}	Minimum Removal Time, Clear to Clock		-2	0	ns
t _S	Minimum Setup Time Data to Clock		12	20	ns
t _H	Minimum Hold Time Clock to Data		1	5	ns
t _W	Minimum Pulse Width Clear or Clock		10	16	ns

AC Electrical Characteristics

 $C_L = 50 \text{ pF}, t_f = t_f = 6 \text{ ns} \text{ (unless otherwise specified)}$

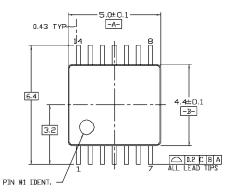
Symbol	Parameter	Conditions	v _{cc}	$T_A = 25^{\circ}C$		$T_A = -40 \text{ to } 85^{\circ}\text{C}$	T _A = -55 to 125°C	Units
				Тур		Guaranteed Limits		
f _{MAX}	Maximum Operating Frequency		2.0V		5	4	3	
			4.5V	1	27	21	18	MHz
			6.0V	1	31	24	20	
t _{PHL} , t _{PLH}	Maximum Propagation Delay		2.0V	115	175	218	254	
	Clock to Output		4.5V	13	35	44	51	ns
			6.0V	20	30	38	44	
t _{PHL}	Maximum Propagation Delay		2.0V	140	205	256	297	
	Clear to Output		4.5V	28	41	51	59	ns
	·		6.0V	24	35	44	51	
t _{REM}	Minimum Removal Time		2.0V	-7	0	0	0	
112	Clear to Clock		4.5V	-3	0	0	0	ns
			6.0V	-2	0	0	0	
t _S	Minimum Setup Time		2.0V	25	100	125	150	
3	Data to Clock		4.5V	14	20	25	30	ns
			6.0V	12	17	21	25	
t _H	Minimum Hold Time		2.0V	-2	5	5	5	
	Clock to Data		4.5V	0	5	5	5	ns
			6.0V	1	5	5	5	
t _W	Minimum Pulse Width		2.0V	22	80	100	120	
••	Clear or Clock		4.5V	11	16	20	24	ns
			6.0V	10	14	18	20	
t _{THL} , t _{TLH}	Maximum Output		2.0V		75	95	110	
	Rise and Fall Time		4.5V	1	15	19	22	ns
			6.0V	ĺ	13	16	19	
t _r , t _f	Maximum Input		2.0V		1000	1000	1000	
·	Rise and Fall Time		4.5V	1	500	500	500	ns
			6.0V	ĺ	400	400	400	
C _{PD}	Power Dissipation Capacitance (Note 5)	(per package)	5.0V	150				pF
C _{IN}	Maximum Input Capacitance		 	5	10	10	10	pF

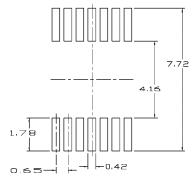
Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$.



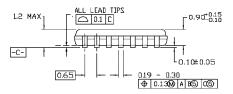
14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A

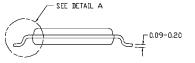
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)





LAND PATTERN RECOMMENDATION

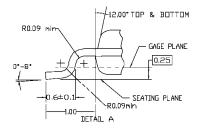




NOTES:

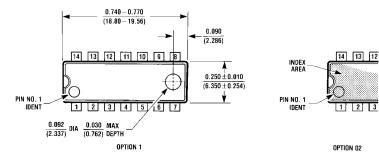
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB_ REF NOTE 6, DATED 7/93
- B. DIMENSIONS ARE IN MILLIMETERS
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

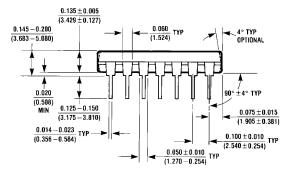
MTC14revD

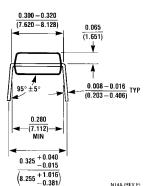


14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)







14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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